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PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No.	:	10/667,825	Confirmation No.: 1009
Applicant(s)	:	Giuseppe Pedretti, et al.	
Filed	:	September 22, 2003	
TC/A.U.	:	3729	
Examiner	:	Thiem D. Phan	
Title	:	Process for Manufacture of Printed Circuit Boards with Thick Copper Power Circuitry	
Docket No.	:	8245.060	
Customer No.	:	30589	

Mail Box Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

In response to the Office Action dated October 10, 2006, Applicants
submit the following:

Listing of Claims begins on page 2 of this paper.

Remarks/Arguments begin on page 8 of this paper.